

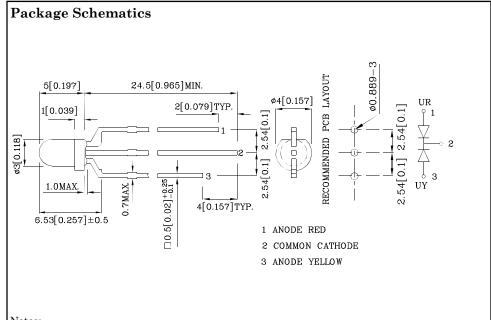
T-1(3mm) BI-COLOR INDICATOR LAMP

Features

- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- RoHS compliant







Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UR (GaAsP/ GaP)	UY (GaAsP/ GaP)	Unit	
Reverse Voltage	$V_{\rm R}$	5	5	V	
Forward Current	I_{F}	30	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	160	140	mA	
Power Dissipation	P_{D}	75	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~	°C		
Storage Temperature	Tstg	-40 ~ +85			
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

Operating Characteristics (T _A =25°C)		UR (GaAsP/ GaP)	UY (GaAsP/ GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	2	2.1	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λΡ	627*	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=20\text{mA})$	λD	617*	588*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	45	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	20	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLUYR34M	Red	GaAsP/GaP	White Diffused -	15 8*	39 15*	627*	60°
	Yellow	GaAsP/GaP		10 10*	19 19*	590*	

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Dec 19,2013

XDSA2561 V7-X Layout: Maggie L.

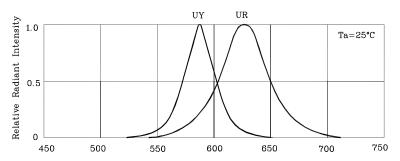


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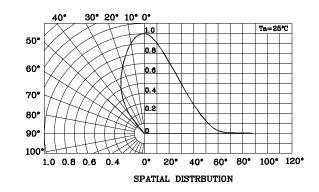
Part Number: XLUYR34M



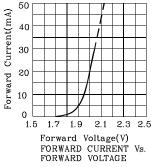


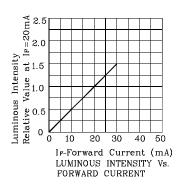


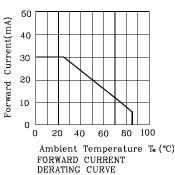
wavelength λ (nm) RELATIVE INTENSITY Vs. CIE WAVELENGTH

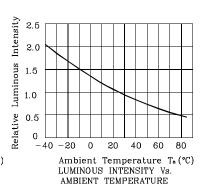


UR

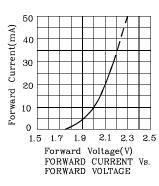


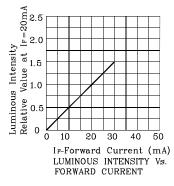


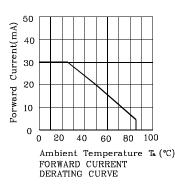


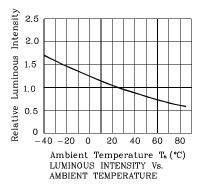


UY

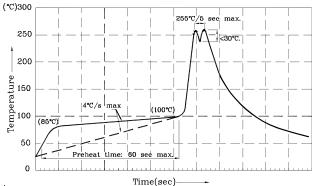








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



- 1. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec
- (5 sec max).
- (8 sec links).

 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.

 4.Fixtures should not incur stress on the component when mounting and during soldering process.

 5.SAC 305 solder alloy is recommended.

 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

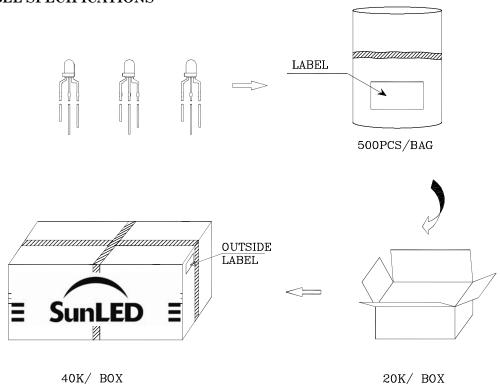
Note: Accuracy may depend on the sorting parameters.

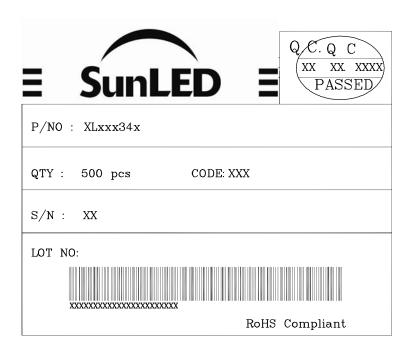




PACKING & LABEL SPECIFICATIONS

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Dec 19,2013